CLAIMS

1. A tape for electronic device packaging, comprising:

a pressure-sensitive adhesive tape having a base film and a pressure-sensitive adhesive layer; and

a laminate of an adhesive layer and a metal layer provided by laminating on a surface of the pressure-sensitive adhesive layer, the surface being on the opposite side of the base film,

the pressure-sensitive adhesive layer, the adhesive layer, and the metal layer are provided in this order,

wherein the adhesive layer at 23°C, a peeling angle of 180° and a linear velocity of 300 mm/min in the B-stage, and

the metal layer has a tensile strength of 350 MPa or higher.

2. The tape for electronic device packaging according to claim 1, wherein the metal layer contains copper or aluminum.

3. The tape for electronic device packaging according to claim 1 or 2, wherein the metal layer has a copper content of 99.95% or less.

4. The tape for electronic device packaging according to any one of claims 1 to 3, wherein the metal layer is a copper alloy foil or an aluminum alloy foil.

5. The tape for electronic device packaging according to any one of claims 1 to 4, wherein the metal layer comprises an alloy including copper and one kind or two or more kinds selected from the group consisting of nickel, chromium, zirconium, zinc, tin, titanium, silicon, iron, manganese,